TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSIII)

# **TPC8108**

Lithium Ion Battery Applications Notebook PC Applications Portable Equipment Applications

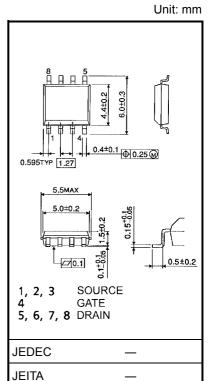
- Small footprint due to small and thin package
- Low drain-source ON resistance:  $RDS(ON) = 9.5 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance:  $|Y_{fs}| = 24 \text{ S (typ.)}$
- Low leakage current:  $I_{DSS} = -10 \mu A \text{ (max) (V}_{DS} = -30 \text{ V)}$
- Enhancement-mode:  $V_{th} = -0.8 \text{ to } -2.0 \text{ V (V}_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA})$

#### **Maximum Ratings (Ta = 25°C)**

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	-30	V	
Drain-gate voltage (F	$R_{GS} = 20 \text{ k}\Omega$ )	$V_{DGR}$	-30	V	
Gate-source voltage		$V_{GSS}$	±20	V	
Drain current	DC (Note 1)	ΙD	-11	Α	
Brain current	Pulse (Note 1)	$I_{DP}$	-44	A	
Drain power dissipati	on $(t = 10 s)$ (Note 2a)	$P_{D}$	1.9	W	
Drain power dissipation $(t = 10 s)$ (Note 2b)		$P_{D}$	1.0	W	
Single pulse avalanc	he energy (Note 3)	E <sub>AS</sub>	157	mJ	
Avalanche current		I <sub>AR</sub>	-11	Α	
Repetitive avalanche	energy Note 2a) (Note 4)	E <sub>AR</sub>	0.19	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55 to 150	°C	

Note: For (Note 1), (Note 2), (Note 3) and (Note 4), please refer to the next page.

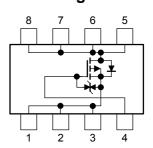
This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.080 g (typ.)

**TOSHIBA** 

### **Circuit Configuration**

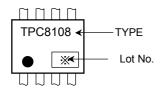


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#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2a)	R <sub>th (ch-a)</sub>	65.8	°C/W
Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2b)	R <sub>th (ch-a)</sub>	125	°C/W

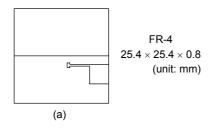
### Marking (Note 5)

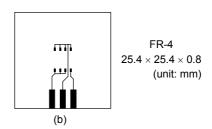


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)





Note 3:  $V_{DD} = -24~V,~T_{ch} = 25^{\circ}C$  (initial), L = 1.0 mH, R<sub>G</sub> = 25  $\Omega,~I_{AR} = -11~A$ 

Note 4: Repetitive rating; pulse width limited by maximum channel temperature

Note 5: • on lower left of the marking indicates Pin 1.

Weekly code: (Three digits)
 Week of manufacture

 (01 for first week of year, continues up to 52 or 53)

 Year of manufacture

 (One low-order digits of calendar year)

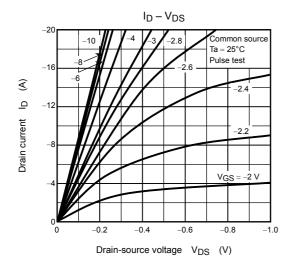
# Electrical Characteristics (Ta = 25°C)

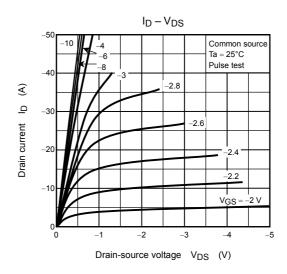
Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ	
Drain cut-OFF cu	rrent	I <sub>DSS</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	_	— — –10		μА	
Drain-source breakdown voltage		V <sub>(BR) DSS</sub>	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-30	_	_	V	
Diani-source brea	akdown voltage	V (BR) DSX	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-15 — — -0.8 — -2.0		·		
Gate threshold vo	oltage	V <sub>th</sub>	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$	-0.8	_	-2.0	V	
Drain source ON	registance	_	$V_{GS} = -4 \text{ V}, I_D = -5.5 \text{ A}$	_	18.5	23	mO	
Drain-source ON resistance		R <sub>DS (ON)</sub>	$V_{GS} = -10 \text{ V}, I_D = -5.5 \text{ A}$	_	9.5	13	mΩ	
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = -10 \text{ V}, I_D = -5.5 \text{ A}$	. 12 24 —		_	S	
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	3510	_	pF	
Reverse transfer capacitance		C <sub>rss</sub>		_	250	_		
Output capacitance		C <sub>oss</sub>		_	600	_		
Rise	Rise time	t <sub>r</sub>	0 V 7 F ln = -5.5 A	_	7	_		
Switching time	Turn-ON time	t <sub>on</sub>	$V_{GS} = 0 \text{ V}$ $V_{GS} = 0 \text{ V}$ $V_{GS} = 0 \text{ V}$ $V_{OUT} = 0 \text{ C}$	_	16	_	20	
Switching time	Fall time	t <sub>f</sub>	4.7.0 4.0 4.0 4.0 4.0 4.0 4.0 4.0 4	_	66	_	ns	
	Turn-OFF time	t <sub>off</sub>	$V_{DD} \simeq -15 \text{ V}$ Duty $\leq$ 1%, $t_W = 10 \mu\text{s}$	_	230	_		
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq -24 \text{ V}, V_{GS} = -10 \text{ V},$ $I_{D} = -11 \text{ A}$		77		nC	
Gate-source charge 1		Q <sub>gs1</sub>		_	7.0	_		
Gate-drain ("miller") charge		Q <sub>gd</sub>			20	_		

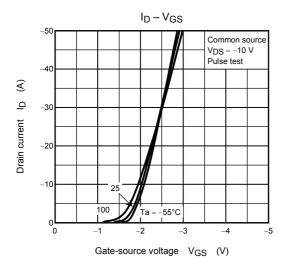
## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

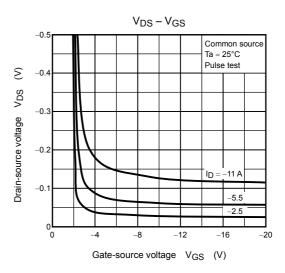
Characteri	stics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse	(Note 1)	I <sub>DRP</sub>	_	_	_	-44	Α
Forward voltage (diode)			$V_{DSF}$	$I_{DR} = -11 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

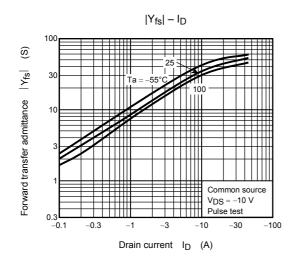
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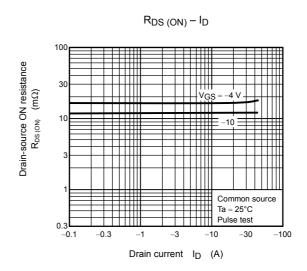


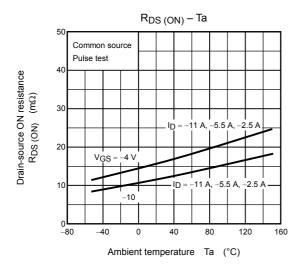


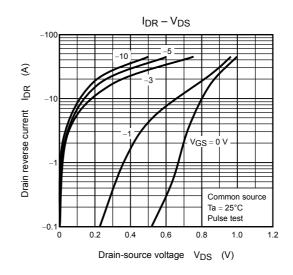


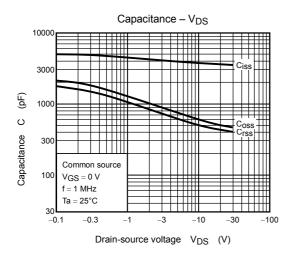


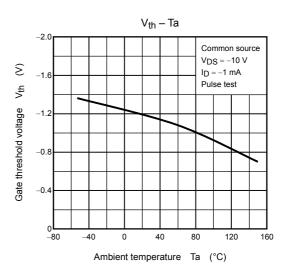


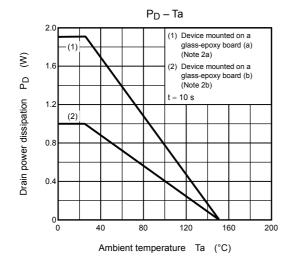


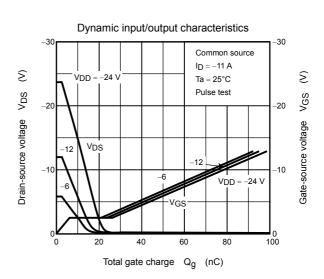


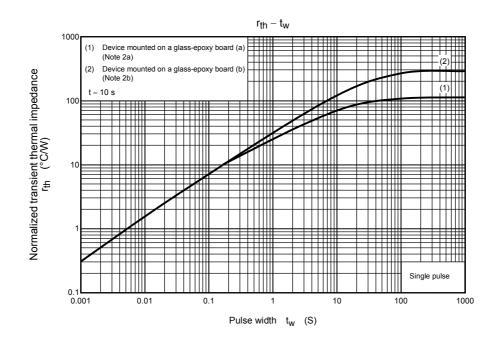


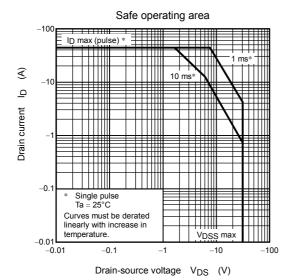












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